CLAIMS

1. A composite sheet for protective film formation comprising a supporting sheet and a film for protective film formation provided on the supporting sheet, wherein

the supporting sheet comprising a substrate, and an adhesive layer laminated to the substrate,

a surface roughness (Ra) of a surface of the substrate on a side on which the adhesive layer is provided is 0.4 μm or less,

a surface roughness (Ra) of a surface of the substrate on an opposite side from the side on which the adhesive layer is provided is greater than the surface roughness of the surface on the side on which the adhesive layer is provided, and is from 0.053 to 0.48 μm,

the substrate and the adhesive layer exhibit both of transmittance to light having a wavelength of 532 nm and light having a wavelength of 1,600 nm,

the storage modulus of the adhesive layer is at least 30 kPa,

the film for protective film formation is for protecting a semiconductor wafer or a semiconductor chip, and

the film for protective film formation is provided on the adhesive layer in the supporting sheet.

2. The composite sheet for protective film formation according to Claim 1, wherein

the surface roughness (Ra) of the surface of the substrate on the opposite side from the side on which the adhesive layer is provided is 0.15 to 0.48 μm.

3. The composite sheet for protective film formation according to Claim 1 or 2, wherein a thickness of the adhesive layer is 15 μm or less.

4. The composite sheet for protective film formation according to any one of Claims 1 to 3, wherein the adhesive layer is non-energy-curable.